

# ONE SOURCE ONE SOLUTION



## Die & Wafer Solutions



- Largest Global Die Distributor
- Next-Gen Materials: GaN, SiC
- Die Express Quick Turn Service
- Turnkey Wafer Processing: Wafer Thinning & Dicing, Pick & Place, Wafer Probe, Mapping & Inking, Visual Inspection
- Customized Output: Sawn on Foil, Waffle Pack, Gel-Pak, Tape & Reel
- Vendor Managed Inventory, Long Term Die & Wafer Storage
- EOL Die Sustainment Program
- Lot Acceptance Testing & Element Evaluation

## Hi-Rel Products



- Memory, Logic, Analog, DC-DC Hybrids & PCBs, RF/Microwave, Diodes, Data Bus, SMD/5962, Couplers & Harnesses
- Packaging & Assembly: Precision Die Attach, Optoelectronic
- Hermetic: DIP, SOJ, LCC, FP, QFP, Gull Wing, PGA, Metal Can
- Plastic: CSP, BGA, QFN, ZIP
- QML Level Packaging
- Advanced Packaging: Flip-Chip/MCM, 2.5/3DHI, SiP, Chiplets, WLP, Novel Microfabrication
- Custom ASICs
- Turnkey Assembly, Test & Kitting

## Testing & Qualification



- Electrical & Environmental Testing
- Device Characterization Testing
- FPGA, ASIC, RF, Memory, Analog, Logic, Mixed Signal & Discrete
- DMEA Trusted Source for Test and Process Screening
- PEMs/COTS Upscreening & Qual, Reliability Testing
- Advanced Chamberless Burn-In, HTOL/TOL
- ESD Characterization
- Acoustic Microscopy, X-Ray, XRF, PIND, Fine/Gross Leak Testing
- Counterfeit Mitigation Services

## Component Modification



- Robotic Hot Solder Dip
- BGA Reballing
- CGA Attach
- Component Prep. & Lead Attach
- Trim & Form, and Reconditioning
- Component Harvesting
- Support Solutions: Tape & Reel, Marking, Labeling & Kitting, Bake & Package, IC Program, 3D Scan
- Supplier Managed Inventory (SMI)
- Serving All Standard Package Types
- NADCAP Certified

### One Source Sustainment Solutions - Keeping Mission Critical Systems & Platforms Operational

#### Original Qualified Product

With access to the broadest supply of die, we will source originally qualified parts that have or will become EOL, avoiding costly requalification.

#### Form-Fit-Function Recreation

When original qualified die or components are not available, Micross has the expertise to reverse engineer devices and recreate equivalent devices.

#### Program Sustainment Management

Uninterrupted product supply through BOM monitoring, long term die & wafer storage and turnkey and supplier managed inventory



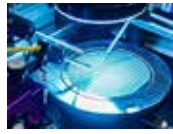
## Facilities & Locations

17 World Class Manufacturing Operations (550,000+ ft<sup>2</sup>) in North America & Europe. AS9100 & ISO9001 Certified.

### Die & Wafer Solutions



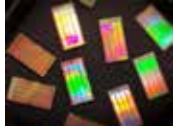
**Apopka, FL**  
**Die & Wafer Solutions**  
Wafer Processing & Test, Bare Die & Wafer Distribution



**Los Alamitos, CA**  
**SemiDice**  
Wafer Processing & Test, Bare Die & Wafer Distribution



**Milpitas, CA**  
**Silicon Turnkey Solutions**  
Electrical and Reliability Test, COTS/PEMs Upscreening & Qualification



**Woburn, MA**  
**Micross Express**  
Bare Die & Wafer Distribution, Passive Components, Same-Day Service, & Vendor Managed Inventory



**Norwich, UK**  
**Die & Wafer Solutions**  
Wafer Processing & Test, Bare Die & Wafer Distribution



**Clearwater, FL**  
**Counterfeit Mitigation**  
Counterfeit Detection Testing, Upscreening, and IC Programming

### Hi-Rel Products



**Apopka, FL**  
**Hi-Rel Components**  
MCM / Hybrid Packaging, Assembly, Test and Hi-Rel Products



**San Jose, CA**  
**Hi-Rel Power Solutions**  
Hybrid DC-DC Converters and EMI Filters



**Shirley, MA**  
**Hi-Rel RF Solutions**  
GaN / GaAs RF & Microwave Switches, Amplifiers, & Attenuators



**Sunrise, FL**  
**Couplers & Harnesses**  
Hi-Rel MIL-STD-1553 Data Bus Couplers and Harness Assemblies



**Raleigh, NC**  
**Adv. Interconnect Technology**  
2.5/3D Heterogeneous Integration & Wafer Level Packaging (WLP)



**Reynosa, MX**  
**Hi-Rel Diodes**  
Hi-Rel Discrete Diodes and Assemblies (ISOPAC®)



**Herlev, DK**  
**Hi-Rel Power Solutions**  
COTS and Custom Board-Based Power Products



**Portsmouth, UK**  
**Hi-Rel Components**  
MCM / Hybrid Packaging, Assembly, Test, and Hi-Rel Products

### Component Modification Services



**Manchester, NH**  
**Component Modification**  
Robotic Hot Solder Dip (RHSD), Lead Attach, and Trim & Form



**Round Rock, TX**  
**Component Modification**  
BGA Reballing, Components Harvesting, and Solderability



**Crewe, UK**  
**Component Modification**  
Robotic Hot Solder Dip (RHSD), TCE, BGA Reballing, CGA, and Plating

### Corporate Headquarters



**Melville, NY**  
**Micross Headquarters**

### Engineering & Program Management Support

Micross' highly experienced global field sales, and expert engineering teams provide complete application support from design specification to post production sustainment & program management.

### Micross Heritage

With Over 45+ Years Experience, Micross has Strengthened it's Capabilities to Offer the Broadest Microelectronic Solutions Available from One Source.



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